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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2007 [Approved on 29 November 2021, 12:19 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.89%	Nickel REACH Article 67 Exemption	8049-31-8	1.5%
			Silicon dioxide Exempt from other regulatory requirements	14808-60-7	5.05%
			Silicon	7440-21-3	93.45%
Die attach	Sn-Pb solder	4.37%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	44.78%	Carbon black	1333-86-4	0.5%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			Tetrabromobisphenol A Exempt from other regulatory requirements	79-94-7	0.99%
			ALUMINUM(III) HYDROXIDE	21645-51-2	2.8%
			resin	9060-05-3	8.6%
			Epoxy resin 89	26335-32-0	16.21%
			Silica, Crystalline Exempt from other regulatory requirements	14808-60-7	70.1%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadfinish	Tin plating	0.55%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.41%	iron	14127-53-8	0.1%
			Copper	7440-50-8	99.9%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123FL	Diode SMD	0.018	g